Title (en)

METHOD FOR PRODUCING A COMPONENT ASSEMBLY FOR A PACKAGE, METHOD FOR PRODUCING A PACKAGE HAVING A COMPONENT ASSEMBLY, COMPONENT ASSEMBLY, AND PACKAGE

Title (de)

VERFAHREN ZUM HERSTELLEN EINER BAUTEILANORDNUNG FÜR EIN PACKAGE, VERFAHREN ZUM HERSTELLEN EINES PACKAGES MIT EINER BAUTEILANORDNUNG, BAUTEILANORDNUNG UND PACKAGE

Title (fr)

PROCÉDÉ DE FABRICATION D'UN AGENCEMENT DE COMPOSANTS POUR UN BOÎTIER, PROCÉDÉ DE FABRICATION D'UN BOÎTIER CONTENANT UN AGENCEMENT DE COMPOSANTS, AGENCEMENT DE COMPOSANTS ET BOÎTIER

Publication

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Application

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Abstract (en)

[origin: WO2020259755A1] The invention relates to a method for producing a component assembly for a package, said method comprising: providing a wafer (1) made of a semiconductor material having a polished wafer surface (6); forming an opening (2,3) in the wafer (1) by means of anisotropic etching, wherein an anisotropically etched surface (4) is produced in the region of the opening (2,3); dicing a component (9) from the anisotropically etched wafer, wherein the diced component (9) is produced with the following areas: an optical area (7) which is formed in the region of a surface portion of the polished wafer surface (6), and a mounting area (5) which is formed in the region of the anisotropically etched surface (4); and mounting the diced component (9) on a substrate surface (11) of a carrier substrate (12), using the mounting area (5), such that the anisotropically etched surface (4) is bonded to the substrate surface (11), wherein the optical area (7) is arranged as an inclined, exposed area. A component assembly and a package having a component assembly are also provided.

IPC 8 full level

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